

# **2018 19th International Conference on Electronic Packaging Technology (ICEPT 2018)**

**Shanghai, China  
8-11 August 2018**

**Pages 1-584**



**IEEE Catalog Number: CFP18553-POD  
ISBN: 978-1-5386-6387-5**

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IEEE Catalog Number:	CFP18553-POD
ISBN (Print-On-Demand):	978-1-5386-6387-5
ISBN (Online):	978-1-5386-6386-8

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# Table of Contents

Research on Large Area Soldering Process for Microwave RF Module Based on DOE Method·····	1
<i>Dayuan Jin, Xin Xie and Yun Wan</i>	
MDS Investigation on the Melting and Solidification of Silver Nanoparticles ·····	5
<i>Yan Zhang, Guoqiang Zhang, Qiaoran Zhang, Xiuzhen Lu and Johan Liu</i>	
Effect of Temperature on Electrochemical Corrosion of Zn-30Sn Lead-free Solder ·····	10
<i>Zhenghong Wang, Zelin Yang, Shenbo Zeng, Gong Zhang, Jianchun Liu, Chuantong Chen and Katsuaki Sukanuma</i>	
Effect of Oxygen on the Ag Sintering Technology with Low Temperature Pressureless ·····	15
<i>Chuantong Chen, Chanyang Choe, Zheng Zhang, Shijo Nagao and Katsuaki Sukanuma</i>	
The Design and Optimize of Glass Diode Sealing Graphite Boat by Thermal-electric Coupling Analysis ·····	19
<i>Peng Wu, Chenyi Dai and Ruiqiang Mu</i>	
Thermal Networks Generation and Application in IGBT Module Packaging ·····	23
<i>Daohui Li and Xiang Li</i>	
Novel 3.3kV Si-SiC Hybrid Power Module ·····	27
<i>Daohui Li and Xiang Li</i>	
Research on Reliability of LED Luminaires in Extreme Natural Environment ·····	31
<i>Zhonghong Shen, Chunxia Wang, Xiaoqun Dong, Huawei Xu, Jiang Xia and Jianyao Hu</i>	
Plasma Treatment Technology in Microwave Printed Circuit Board Manufacturing·····	36
<i>Guangqian Dai, Ce Zeng, Xiaolin Gong, Fangsheng Bian, Yumin Lin and Zhihui Liu</i>	
A Strain Controllable Board Level Bending Method for PoP Package Reliability Validation·····	41
<i>Jeffrey Lee, Lane Brown and Feng Lu</i>	
Optimal design of Reliability and Signal integrity for Embedded micro-scale BGA Solder Joint·····	47
<i>Liangkun Lu, Chunyue Huang, Jianpei Wang and Wei He</i>	
Gallium Arsenide Power Amplifier Failure Analysis·····	52
<i>Pengbo Jiang, Jie Chen, Zongzhi Duan, Shengxiang Bao, Yongda Hu, Qiang Li, Chuan Luo, Tao Hong, Libo Ai and Huan Liu</i>	
Mechanical and Warpage Characterization of Glass Carrier in Fan-out Technology Development ·····	55
<i>Janae Ho and Ryan Chen</i>	

Design and Fabrication of Glass-based Integrated Passive Device .....	59
<i>Peng Sun, Yuhong Zhou, Sima Ge and Liqiang Cao</i>	
Sidewall Protection for a Wafer Level Chip Scale Package .....	64
<i>Peng Sun, Jun Liu, Xu Cheng and Liqiang Cao</i>	
Effect of Active Agents on the Rheological Properties of SnAgCu Solder Pastes Used for Jetting Printing .....	69
<i>Saipeng Li, Xuemei Zhang, Jian Hao, Jian Zhou and Feng Xue</i>	
Fabricating Additive Fine Lines through Selective Surface Modification for WLP-PI layer .....	74
<i>Yuefeng Wang, Yan Hong, Guoyun Zhou, Wei He*, Zhengping Gao*, Shouxu Wang, Xin Zhou, Xinhong Su and Yongsuan Hu</i>	
Molecular Dynamics Simulation on Grinding Process of Cu-Si and Cu-SiO <sub>2</sub> Composite Structures .....	79
<i>Yixin Xu, Fulong Zhu, Miaocao Wang, Xiaojian Liu and Sheng Liu</i>	
Development of Auto Infrared Photoelastic Microscope for Stress Measurement of Silicon .....	84
<i>Tenghui Li, Ruixia Yao, Chuan Yu and Fei Su</i>	
Bosch Etching Study with Large Open Rate and Depth Application .....	89
<i>Yulong Ren, Zhen Huang, Fei Geng and Peng Sun</i>	
Thermal Shock Reliability of GaN Die-attached on DBA with Ag Sinter Paste .....	93
<i>Dongjin Kim, Chuantong Chen, Pei Chun, Zheng Zhang, Shijo Nagao, Aiji Suetake, Tohru Sugahara and Katsuaki Suganuma</i>	
Failure Analysis of a Chip Carrier Board .....	97
<i>Xiaoyu Fang and Yue Dong</i>	
Research on Vibration Suppression of High-speed IC Packaging Mechanism Based on Cross-Bee PID Algorithm .....	100
<i>Lezhi Ye, Hongtao Wang, Haiming Wang and Desheng Li</i>	
Thermal Stress Analysis of BGA Solder Joint Power Load Based on COMSOL .....	104
<i>Jianpei Wang, Chunyue Huang, Liangkun Lu and Wei He</i>	
Hetero-connecting Materials Effect on the Electromigration and Thermal Migration of SnBi Solder Joints .....	109
<i>Ming Liu, Limin Ma, Fu Guo, Yishu Wang and Jing Han</i>	
Using RBF Algorithm for Scanning Acoustic Microscopy Inspection of Flip Chip .....	112
<i>Fan Liu, Mengying Fan, Zhenzhi He and Xiangning Lu</i>	
Transient Thermal Characterization of Junction to Case Thermal Resistance for 2.5D Packages .....	115

*Hengyun Zhang, Yang Sui, Tingyu Lin and Haiyan Liu*

High Mechanical Dual-Interface FSID COB Development for 15N 3Wheel Test····· 121

*Haomin Bao, Lei Xu, Yonghua Zhou and Jianfeng Zeng*

Cantilever Gold Ribbon Bonding used in MMCM ····· 125

*Zongjie Han, Le Jie, Wei Yan, Yongfang Hu and Xiaoxuan Li*

Process Development and Failure Analysis for Chip-Last Panel Level Fan-out Packaging (PLP) ····· 129

*Haiyan Liu, Tingyu Lin, Fengze Hou, Feng Chen, Hengyun Zhang and Liqiang Cao*

Influence of Cu Nanoparticles on Interfacial Reaction and Cu<sub>6</sub>Sn<sub>5</sub> Growth Behavior in Sn/Cu Joints ·· 135

*Shengyan Shang, Anil Kunwar, Yanfeng Wang, Jinye Yao, Haitao Ma and Yunpeng Wang*

Application of AOI Light Source Modes in Multi-Chip Modules Inspection ····· 141

*Yilong Wu, Junling Wen and Pingsheng Zhang*

Fabrication of Anti-Counterfeiting Micro-fingerprints on Signatures Based on Ion Wind ····· 144

*Shangru Zhou, Yuping Yan, Jie Liu, Huai Zheng and Sheng Liu*

Failure Analysis Examination of the Effect of Thermal Cycling on Copper-filled TSV Interposer Reliability·· 148

*Yuan Chen, Peng Zhang, Wei Su and Xiaoling Lin*

Thermal Simulation into the Effect of Varying Encapsulant Media on Wire Bond Stress Under Temperature Cycling····· 152

*Matt Packwood, Daohui Li and Paul Mumby-Croft*

An Numerical Method for the Optimization of IGBT Modules····· 156

*Hua Lu, Pushparajah Rajaguru and Chris Bailey*

Study of the Fabrication and Organization Properties of Copper-based Ba<sub>1-x</sub>Sr<sub>x</sub>TiO<sub>3</sub> Composites ····· 161

*Shouwei Li, Pei Liang, Xuefei Ming and Zhiqiang Xiao*

Study of the Fast Sintering of Silver Nanoparticle Ink Induced by Sodium chloride solution at Room Temperature ····· 165

*Yong Xiao, Zhihao Zhang, Ming Yang, Haifeng Yang, Mingyu Li and Yong Cao*

Electrical Stressing and Self-Heating Effects on GaN-based LEDs' Degradation Under Extremely Low Temperature ····· 168

*Bing Yan, Dongdong Teng, Lilin Liu and Gang Wang*

Study on Bonding Strength of Sintered Nano-silver Joint on Bare Copper Substrates with Different Grain Sizes · 176

*Cheng-Jie Du, Xin Li and Yun-Hui Mei*

Effect of Blade Dicing Parameters on Die Strength .....	180
<i>Mengyuan Xue, Tao Chen, Xundi Zhang, Huiqin Ling, Liming Gao and Ming Li</i>	
The Corrosion Behavior of Au/Al Interface Under High Accelerated Stress Test .....	184
<i>Tao Chen, Mengyuan Xue, Xundi Zhang, Liming Gao and Ming Li</i>	
Effect of Ni Barrier Layer Thickness on IMCs Evolution in $\Phi 5\mu\text{m}$ Cu/Ni/Sn Pillar Bumps .....	190
<i>Kai Chen, Huiqin Ling, Fayao Guo, Ming Li, Wenqi Zhang and Liqiang Cao</i>	
Silicon Nanowires Passivated by TiO <sub>2</sub> Layer for Supercapacitors in Aqueous Electrolyte .....	195
<i>Cheng Zhang, Shuang Tian, Liyi Li, Feng Xue, Jian Zhou and Ching-Ping Wong</i>	
The Optimum Pre Calibration Curve of Power Amplifier .....	200
<i>Yaohua Chen, Chaoshi Cai and Qun Chen</i>	
Optimize FT Hardware Design by RSS Tolerance Analysis Method .....	206
<i>Chunhua Zhao and Luxin Cao</i>	
Stress and Strain Analysis of LTCC Substrate Module based on Microchannel .....	210
<i>He Wei, Chunyue Huang, Liangkun Lu and Jianpei Wang</i>	
Through Glass Via Technology for Ultra-High Q Factor Inductors .....	215
<i>Xiufeng Zhou, Jianfeng Wang and Xuefei Ming</i>	
Warpage Analysis of High-density FC-PBGA Device During Package Process .....	219
<i>Xin Yao, Xuefei Ming and Yuyuan Cao</i>	
A Study of the Content of Ionizable Surface Contaminants and Corrosion of PCB .....	223
<i>Yingjie Zhang, Bin Chen, Peiqiang Zhang and Zilian Liu</i>	
Molecular Dynamic Simulation of Grain Size and Work Temperature Effect on Mechanical Properties of Polycrystalline Copper .....	228
<i>Zhiwei Zhang, Pei Chen and Fei Qin</i>	
Modeling of Equivalent Thermal Conductivity of Power Delivery Network in 3D Packages .....	233
<i>Weijun Zhu and Gang Dong</i>	
Design of LC Bandpass Filters Based on silicon based IPD Technology .....	238
<i>Chongchong Mao, Yetao Zhu, Zhu'An Li and Xuefei Ming</i>	
Process Development and Reliability for Wafer-level 3D IC Integration Using Micro-bump/Adhesive Hybrid Bonding and Via-last TSVs .....	241
<i>Mingjun Yao, Ning Zhao, Daquan Yu, Zhiyi Xiao and Haitao Ma</i>	

Failure Localizations on the Open Circuit for a High Density Ceramic Flip-Chip Package after Reliability Test .....	247
<i>Han Li, Hongyu Zheng and Xiaojun Zhang</i>	
Study on Characterization of Light Aging of RGB LED Packaging Materials.....	252
<i>Zhentao Deng, Dayong Gui, Menglong Tu, Lin Xie and Mingliang Wang</i>	
A Low-Pass Filter Made Up of the Cylindrical Through-Silicon-Via .....	257
<i>Fengjuan Wang, Jia Huang and Ningmei Yu</i>	
An Online-Sintering Approach for Bonding High-Power Devices Using Nanosilver Paste.....	260
<i>Haidong Yan, Weiyong Ma, Yunhui Mei and Daoguo Yang</i>	
Effect of Ag Element on Microstructure and Mechanical Properties of Sn-Bi-xAg solders designed by Cluster-Plus-Glue-Atom Model .....	265
<i>Jing Ren, Mingliang Huang and Xudong Yang</i>	
Polypyrrole Hollow Nanosphere Intercalated Graphene-based Flexible Supercapacitor .....	270
<i>Yuanyuan Yang, Pengli Zhu, Leicong Zhang, Tingxi Li, Qing Wang, Rong Sun and Chingping Wong</i>	
A Stretchable Translucent Conductive Film Based on Polymer Microspheres Lithography Technology .....	275
<i>Xinyu Zhang, Yougen Hu, Wenlong Jiang, Pengli Zhu and Rong Sun</i>	
Design and Fabrication of the Silicon-based Integrated MIM Capacitors .....	280
<i>Rongzhen Zhang, Qing Zhang, Xiufeng Zhou, Yetao Zhu, Xuefei Ming and Nayan Gao</i>	
Failure Analysis Technology of Lead-free BGA Solder Joints and Relevant Cases .....	284
<i>Wanchun Tian, Qin Wu and Liang Zhou</i>	
Micropypamid Silcon Wafer with ZnO Nanowires as High Efficiency Piezoelectric Nanogenerator .....	288
<i>Xuecheng Yu, Leicong Zhang, Wen Jiang, Pengli Zhu, Rong Sun and Ching-Ping Wong</i>	
Effect of Nickel-plating on Laser Welding of Aluminum Packages .....	292
<i>Jie Chen and Bihui Wang</i>	
Warpage Simulation and Optimization of Fan-Out Wafer Level Package(FO-WLP) with TMV under Different Processes .....	297
<i>Yanhui Guo, Guohua Zhang and Jianfeng Wang</i>	
Thermal Error Analysis and Compensation of Die Attach Equipment for Fan-out Package .....	302
<i>Junshuai Wang, Lezhi Ye, Haiming Wang, Ping Lang and Zhiyue Wang</i>	
Metal-Organic Framework Derived PdCu/C as an Efficient Catalyst for Electroless Copper Deposition	306

<i>Jiahui Chen, Huangqing Ye, Jinqi Xie, Changzeng Yan, Rong Sun and Ching-Ping Wong</i>	
Research on Key Process Technology of RDL-first Fan-out Wafer Level Packaging .....	309
<i>Jiachang Zhu and Xuefei Ming</i>	
Verification and Optimization of the Thermal Design for The Power Stack with Three IGBT Modules .....	314
<i>Jianrui Xue, Xinyu Sun, Liming Gao, Ming Li</i>	
Preparation and Characterization of the Double-Side Adhesive Tape with Reactive Properties and High Thermal Conductivity for Electronic Packaging .....	319
<i>Hao Chang, Baotan Zhang and Rong Sun</i>	
Low and Cryogenic Temperature Mechanical Performance and Fracture Behavior of Micro-Scale Cu/Sn-3.0Ag-0.5Cu/Cu Joints with The Decreasing Dimension .....	324
<i>Wangyun Li and Xinping Zhang</i>	
A High Performance and Low Cost Half Bridge IGBT Planar Power Module.....	329
<i>Jianfeng Li, Jingru Dai, Xi Lin, Ke Li and Christopher Mark Johnson</i>	
Investigation on the Reliability of Chips onto the Flex Substrate with a Non-Conductive Paste for Flex Substrates Pretreated by Argon Plasma .....	338
<i>Chengli Chuang and Yirong Jiang</i>	
Study of Capillary Tip States on the Reliability of Al Wire Bonding in Microelectronic Package .....	343
<i>Dezhi Su, Dan Zhao, Quanwen Wang, Changcheng Wang, Yucheng Niu and Peijie Guan</i>	
SiC MOSFET Threshold-Voltage Instability Under High Temperature Aging .....	347
<i>Yang Liu, Huaiyu Ye, Xianping Chen, Zhaohui Zhao, Zhigang Li, Caitao Lu, Jingguo Zhang, Sau Wee Koh, Ligen Wang and Guoqi Zhang</i>	
Random Vibration Simulation on Electronic Equipment with Micro-Systems Using Substructure Method .....	351
<i>Fang Yu, Ning Zhang, Jun Li and Lan Zhan</i>	
Tin Nanoparticles Modified Nano-Silver Paste for Pressureless Low-Temperature Sintering Process ...	356
<i>Qiwang Chen, Xiao Ma, Haijun Huang, Can Yin, Minbo Zhou and Xinping Zhang</i>	
Three-Dimensional Simulation of the Effects of Cu Protrusion of Cu-filled TSVs on Thermal Fatigue Behavior of Micro-Bump Joints in 3D Integration .....	361
<i>Jieying Zhou, Cheng Wei, Shuibao Liang, Han Jiang, Xiao Ma and Xinping Zhang</i>	
A Risk Assessment Method for Void in SnAg Solder Bump Influence on Reliability of Flip Chip Packaging ..	367
<i>Jun Chen, Anmin Hu, Xinjiang Long and Ming Li</i>	



Reliability of High Density Wire Bonding in X Band T/R Module .....	372
<i>Dongliang Wang, Lihua Chen and Feifan Yan</i>	
Phase Field Study of the Combined Effects of Electromigration and Thermomigration On Phase Segregation and Physical Properties of Sn58Bi Solder Joints Under Electric Current Stressing Coupled with Temperature Gradient .....	376
<i>Shuibao Liang, Changbo Ke, Cheng Wei, Minbo Zhou and Xinping Zhang</i>	
Mechanism of Cu <sub>5</sub> Zn <sub>8</sub> Layer Act as A Diffusion Barrier Layer .....	383
<i>Jinye Yao, Hua Li, Ru Huang, Xiao Qi, Boyin Wang, Junshan Qiao, Yunpeng Wang and Haitao Ma</i>	
Study on Electrochemical Migration of Sn-0.7Cu .....	387
<i>Xiao Qi, Haoran Ma, Ru Huang, Jinye Yao, Shengyan Shang, Anil Kunwar, Yunpeng Wang and Haitao Ma</i>	
Effect of Solder Volume on Interfacial Reactions between Sn-0.7Cu solder Balls and Cu Pads Under Multiple Reflow .....	391
<i>Ru Huang, Mengrou Xia, Jinye Yao, Xiao Qi, Boyin Wang, Junshan Qiao and Haitao Ma</i>	
Stability of Multilayered Ag/Ag <sub>3</sub> Sn/Sn Films Non-cyanide Electroplated for LED Leadframe .....	396
<i>Shengnan Ji, Chen Wang, Yunpeng Wang, Haitao Ma and Ning Zhao</i>	
Synthesis of Ba{[(Mg <sub>0.8</sub> Zn <sub>0.2</sub> ) <sub>0.98</sub> Y <sub>0.02</sub> ] <sub>1/3</sub> Ta <sub>2/3</sub> }O <sub>3</sub> Microwave Dielectric Ceramics with La <sub>2</sub> O <sub>3</sub> -B <sub>2</sub> O <sub>3</sub> -ZnO Glass for LTCC Application .....	400
<i>Leiyu Yang, Shuren Zhang, Chengli Sun and Xue Dong</i>	
FE Modeling and Analysis on Thermosonic Flip Chip Bonding Process for Cu/low-k Wafer .....	404
<i>Xuezhi Zhang, Jian Gao, Yun Chen, Yunbo He and Xin Chen</i>	
Effects of Reflow Time on the Morphology of Cu <sub>6</sub> Sn <sub>5</sub> in Solder Balls at 250 °C .....	409
<i>Shuo Zhang, Jing Han and Fu Guo</i>	
Effect of EFO Parameters on the HAZ and Bondability of Gold Wire .....	413
<i>Wenyan Zhou, Jianwen Kong, Feifei Kang, Yongjin Wu, Guoxiang Yang, Hongying Pei, Jialin Chen, Jian Lu and Jianhong Yi</i>	
Investigation on Solid State Bonding and IMC Reaction of Cu Pillar Bump/Ni Micro Cones .....	419
<i>Yukun Guo, Anmin Hu and Ming Li</i>	
Effect of Defected Behavior on Interfacial Heat Transferring Performance for HP-LED Packaging Based On Entropy Generation Analysis .....	423
<i>Peng Cui, Miao Cai and Daoguo Yang</i>	

Reliabilities and Stress Analysis of Printed Circuit Boards Interconnect Stress Test .....	428
<i>Ying Yang</i>	
Investigation of Elastic Fields within Through silicon Vias using a Finite Element Model with Thermal Stresses and Joule Heating Present .....	432
<i>Qibiao Zeng, Yuan Gao, Yubao Zhen and Peng Zhou</i>	
Study on Cu-Cr-Zr Alloy Based High Performance Copper Interconnects Technology for Next Generation Flexible Display .....	438
<i>Honglong Ning, Kuankuan Lu, Shibei Hu, Fuxiang Huang, Xianzhe Liu, Hua Xu, Miao Xu, Lei Wang, Rihui Yao and Junbiao Peng</i>	
Effect of Ag Content on Cu <sub>6</sub> Sn <sub>5</sub> Growth Behavior at Sn-Ag/Cu Interface During Multiple Reflows .....	441
<i>Haoran Ma, Jinye Yao, Chen Wang, Shengyan Shang, Yunpeng Wang and Haitao Ma</i>	
Effect of Soldering Temperature on Cross-Interaction at L-S Interface of Linear Cu/SAC305/Ni Solder Joints ...	445
<i>Bingfeng Guo, Ru Huang, Jinye Yao, Xiao Qi, Anil Kunwar, Yupeng Wang and Haitao Ma</i>	
Study on Preparation Process of Au <sub>80</sub> Sn <sub>20</sub> Eutectic Solder on Thin Film Substrate .....	450
<i>Chunyan Yang, Liuhui Li and Yahui Xue</i>	
Fabrication and Properties of Silver Nanowire Flexible Transparent Electrode .....	454
<i>Rihui Yao, Xiaoqing Li, Zhiqiang Fang, Zhihang Li, Muyang Shi, Shangxiong Zhou, Weijian Yuan, Honglong Ning and Junbiao Peng</i>	
Effects of Sb addition on the microstructure and mechanical performance of Sn <sub>58</sub> Bi based alloys and the solder joints .....	457
<i>Jingang Li, Xiao Ma, Minbo Zhou, Xiang Ning and Xinping Zhang</i>	
Influence of Aging Temperature and Time on the Intermetallic Reaction in 15 $\mu$ m Cu/Sn Copper Pillar Bump .....	462
<i>Lei Ye, Chao Huang, Huiqin Ling, Anmin Hu and Ming Li</i>	
Estimating the Constitutive Behaviour of Sintered Silver Nanoparticles by Nanoindentation .....	466
<i>Xu Long, Wenbin Tang, Xiuzhen Lu, Johan Liu, Weijuan Xia, Yanpei Wu and Cheng Zhou</i>	
Porosity Effect on the Constitutive Model of Porous Material Under Nanoindentation .....	472
<i>Hongcun Guo and Xu Long</i>	
Material and Structural Optimization of Fatigue Life of PBGA Under Temperature Cycling .....	477
<i>Wenjie Wang, Yao Yao, Zhenghu Zhu and Xu Long</i>	

Preparation of a Low Temperature Sintering Silver Nanoparticle Ink and the Fabrication of Conductive Patterns on PET Substrate .....	482
<i>Haijun Huang, Minbo Zhou, Can Yin, Qiwan Chen and Xinping Zhang</i>	
Failure Analysis for Vibration Stress on Ball Grid Array Solder Joints .....	486
<i>Zhiqiang Zhao, Chaohui Hu and Fengwei Yin</i>	
Fabrication of an Oxidation-Resistant Submicron Copper Particle Based Conductive Ink and its Sintering Behavior On the Flexible Substrate.....	491
<i>Haijun Huang, Minbo Zhou, Can Yin, Qiwan Chen and Xinping Zhang</i>	
Facile Synthesis of Silver Nanoparticles Decorated Boron Nitride Nanotube Hybrides .....	496
<i>Chenjie Fu, Xiaoliang Zeng, Rong Sun, Jianbin Xu and Ching-Ping Wong</i>	
A Wet Process to Fabricate Silicon Oxide Layer for Through-Silicon-Via Insulator Application .....	501
<i>Haoze Duan, Shuai Zheng, Liming Gao and Ming Li</i>	
Radiation Source Reconstruction based on Artificial Neural Network for Radio Frequency Interference (RFI) Analysis in Complex System .....	506
<i>Yufei Shu and Xingchang Wei</i>	
Interconnecting the Promising Mxenes via Ag Nanowire in Epoxy Nanocomposites for High-Performance Thermal Management Applications .....	510
<i>Changzeng Yan, Chao Ji, Jiahui Chen, Xiaoliang Zeng, Rong Sun and Ching-Ping Wong</i>	
The Impact of Bumping Stress on Cu RDL Structure .....	513
<i>Yulong Xie, Liming Gao, Tony Chen and Ming Li</i>	
Research on Heat Dissipation of a New Rectangular Microchannel Structure Based on Thermal Bimetal.....	517
<i>Weikang Wan, Haihua Li, Qidong Wang and Xiaoxin Liang</i>	
Room Temperature GaN Bonding by Surface Activated Bonding Method .....	521
<i>Fengwen Mu and Tadatomo Suga</i>	
Study of Ultraviolet Assisted Cure Mechanism of the Phosphor/Silicone Composites Used in White LEDs ·	525
<i>Zhen Wang, Jiajie Fan, Jie Liu, Anhua Hu, Cheng Qian, Xuejun Fan and Guoqi Zhang</i>	
Effect of Electromigration on the Microstructural Evolution and Shear Fracture Behavior of Mixed Assembled Cu/Sn-3.0Ag-0.5Cu-ball/Sn-58Bi-paste/Cu Joints in Board-Level Packaging .....	531
<i>Jiaqiang Huang, Minbo Zhou, Xingfei Zhao and Xinping Zhang</i>	
A Modified MEMS-Casting Based TSV Filling Method with Universal Nozzle Piece That Uses Surface	

Trenches as Nozzles .....	536
<i>Jiebin Gu, Xiaoyuan Xia, Weibo Zhang and Xinxin Li</i>	
Effect of Some N-heterocyclic Inhibitors in the soldering Flux on the Corrosion Behavior of Eutectic Sn–58Bi Alloy and Its Solder Paste .....	540
<i>Xiang Ning, Minbo Zhou, Jingang Li and Xinping Zhang</i>	
A Novel Graphene Oxide Millispheres/ Epoxy Resin Composite with Improved Thermal Conductivity	546
<i>Chen Li, Xiaoliang Zeng, Deliang Zhu, Rong Sun, Jianbin Xu and Ching-Ping Wong</i>	
A Novel Method for Alignment Deviation Automatic Correction in Wafer-level Flip-chip Direct Packaging ...	551
<i>Junming Guan, Hui Tang, Sifeng He, Jian Gao, Xin Chen and Chengqiang Cui</i>	
Plastic Deformation Behavior of IMCs in Solder Joints During Nanoindentation.....	556
<i>Fan Yang, Sheng Liu, Li Liu and Zhiwen Chen</i>	
Size Effect on the Interfacial Reaction and IMC Growth of Sn–3.0Ag–0.5Cu/Cu Joints with the Decreasing Joint Size to several Tens of Microns During Reflowing Soldering .....	562
<i>Xingfei Zhao, Minbo Zhou, Tao Sun and Xinping Zhang</i>	
Research and Introduction of the Process Flow of Full-Automatic Wafer Level Flip Chip Machine .....	566
<i>Yunbo He and Wentao Ye</i>	
Hydrothermal Assembly of One-Dimensional Boron Nitride Nanostructures .....	573
<i>Guang Yang, Haixu Wang, Ning Wang, Rong Sun and Ching-Ping Wong</i>	
Effect of Catalysts on Hydrothermal Preparation of Boron Nitride Nanostructures .....	579
<i>Haixu Wang, Guang Yang, Ning Wang, Rong Sun and Chin-Ping Wong</i>	
Thermal Management Technology of IGBT Modules Base on Two-Dimensional Materials .....	585
<i>Jie Bao, Yuan Xu, Nan Jing, Hao Zhao, Yuhai Fu, Yunjie Zhang, Piao Yang, Renxia Ning, Ju He, Zhenhai Chen and Wenyi Xu</i>	
Diffusion Barrier Properties of Electroless Ni-Fe-P coatings in Zn-5Al Solder Joints.....	589
<i>Han Zhang, Zhiwen Chen, Juan Peng and Li Liu</i>	
Rapid Transient Liquid Phase Sintering by Ag-In Solder Pastes for High-temperature Power Electronics.....	593
<i>Dongxiao Zhang, Shengfa Liu, Zhiwen Chen and Li Liu</i>	
Application of Non-UV BG Tape on Assembly of Flip-Chip Package with Copper Pillar Bump .....	599
<i>Yang Yang, Tuobei Sun, Jian Pang and Xiaoli Ren</i>	

Regular and Rapid Growth of Cu <sub>6</sub> Sn <sub>5</sub> Grains at Liquid-phase Sn/(001)Cu Interface by Imposing Temperature Gradient .....	603
<i>Ning Zhao, Shi Chen, Chunying Liu, Yi Zhong, Haitao Ma and Yunpeng Wang</i>	
The Characters of WO <sub>3</sub> Electrochromic Film Prepared by Sol-gel Method .....	607
<i>Honglong Ning, Xiaochen Zhang and Guanguang Zhang</i>	
Effect of Electric Current Stressing on the Shear Strength and Fracture Behavior of Micro-scale BGA Structured Cu/Sn–3.0Ag–0.5Cu/Cu Joints .....	610
<i>Wenkai Le, Xiang Ning, Jiaqiang Huang, Minbo Zhou and Xinping Zhang</i>	
Reliability Analysis of System-in-Package Module Based on Physics of Failure .....	615
<i>Hui Xiao, Shuqiang Liu and Yong Li</i>	
Shear Creep and Fracture Behavior of Micro-scale BGA Structured Cu/Sn–3.0Ag–0.5Cu/Cu Joints Under Electro-thermo-mechanical Coupled Loads .....	620
<i>Wenkai Le, Zhiwei Zhu, Shanshan Cao and Xinping Zhang</i>	
The Study of MLCC Assembly Reliability Based on PCB Strain Measurement .....	625
<i>Weina Gao, Jingming Fei, Jun Wang and Binbin Zhang</i>	
Low Interconnection Loss and Low-cost Approach for Antenna in Package of 77GHz Automotive Radar Applications .....	629
<i>Chengyu Ho, Chenchao Wang, Shengchi Hsieh and Chunyen Ting</i>	
Study of the Curing Kinetics and Heat Resistance of Isotropic Conductive Adhesive .....	633
<i>Jiang Han, Minbo Zhou and Xinping Zhang</i>	
The application and case study of FIB system in the PCB with OSP final finish failure analysis .....	638
<i>Jianghua Shen, Xiao He and Enliang Li</i>	
A Cost-Effective and High Performance Assembly Technology for Interconnecting the Cu/Al Bilayer Electrode and Leadwire of ZnO Varistor Using a Low Ag-containing Solder Paste .....	642
<i>Kai Wang, Guoliang Chen, Minbo Zhou and Xinping Zhang</i>	
Frequency-domain Lifetime Prediction Methods for the PoP Under Wide-band Random Vibration Loading .....	648
<i>Jiang Xia, Zhonghong Shen, Guoyuan Li, Qi Peng, Huawei Xu, Yajiao Yue, Linyi Huang and Binhui Liu</i>	
Fluxless Bump Reflow in Activated Hydrogen Atmosphere .....	652
<i>C. Christine Dong, Fisher Yu, Tim Bao, Wenqi Zhang, Fengwei Dai and Dengfen Yang</i>	
Reliability Improvement of CBGA Solder Ball Joint in LTCC-based SiP Module .....	656

<i>Yangyang Li, Yuanqi Zeng, Dong Dong, Hui Wang, Jiyong Tan and Jifan Zhang</i>	
Research on the Thermal Fatigue Life of CQFN Packaging .....	662
<i>Zhentao Yang, Bo Peng and Ling Gao</i>	
Effect of Ni Thickness on the IMC and Reliability of Ultrathin NiPdAu .....	667
<i>Hongfa Pan, Yibo Wang, Weiguo Luo, Ming Li and Liming Gao</i>	
Effect of Pretreatment on Copper Filling of High Aspect Ratio Through-Silicon Via (TSV) .....	672
<i>Hongfa Pan, Yumei Zhang, Ming Li and Liming Gao</i>	
Corrosion Resistance of Electrodeposited Nanocrystalline Ni from Citrate Baths .....	676
<i>Jiangbing Xia, Hongmo Li, Yuequan Wang, Tao Hang and Ming Li</i>	
Study on Droplet Movement on Superhydrophobic Surfaces under Electric Fields .....	681
<i>Jie Liu, Shangru Zhou, Yuping Yan, Huai Zheng and Sheng Liu</i>	
An Effective Way to Solve the Void Problem of Traditional Underfill Based on NCP Technology .....	687
<i>David Liu, Jianrui Xue, Ming Li and Liming Gao</i>	
Application of Finite Element Simulation Analysis and Calculation in Process Design Optimization .....	691
<i>Yabing Zou, Tao Lu and Xiao He</i>	
Failure Analysis of Insufficient Bonding Strength of Electrolytic Nickel Gold Spring Soldering Interface .....	696
<i>Hui Xu and Feng Xiong</i>	
Effect of Grain Boundary Character and Grain Orientation on Electromigration in Lead-Free Solder Interconnects with Cyclic Twinning Structure .....	701
<i>Xing Fu, Hongtao Chen, Bin Zhou, Si Chen, Ruohe Yao and Xiaoqi He</i>	
Design、Fabrication and Characterization of Si-based Microfluidic Structures for High Heat-flux Cooling Application .....	704
<i>Yangyang Li, Xiancai Chen, Jia Lin, Qian Lu, Jian Zhang and Weiwei Xiang</i>	
Simulation and Optimization of High Performance On-Chip Solenoid MEMS Inductor .....	710
<i>Shengrui Zhou, Jicun Lu and Ling Xu</i>	
Simulation and Low Cost Process Development for Thin Wafer Level TSV Last Integration Scheme for RF Applications .....	716
<i>Md Rahim, Luke England, Yeye Wang, Teng Wang and Daquan Yu</i>	
Directional Solidification Structure and Deformation Behavior of Silver Bonding Wire .....	722
<i>Feifei Kang, Wenyan Zhou, Jianwen Kong, Yongjin Wu, Guoxiang Yang, Hongying Pei and Kunhua Zhang</i>	

Failure Analysis and Case Study of Wire Bonding .....	728
<i>Lili Ma and Hang Chen</i>	
Investigation of ENEPIG/Sn-10Sb Solder Joint .....	731
<i>Xin Gu, Liangsong Huang and Guihui Wang</i>	
Research on Motion Simulation of Wafer Handling Robot Based on SCARA.....	734
<i>Yunbo He and Jiajun Chen</i>	
Simulation Analysis on Thermal Drift of MEMS Sandwich Accelerometer .....	740
<i>Wei Mei, Qifang Hu, Chaoyang Xing, Nannan Li and Yuxin Xu</i>	
The Mechanical Simulation of a Special Biosensor .....	745
<i>Shuaipeng Wang, Hongxun Tian, Xinghui Zhang, Jianqiang Li, Yanning Chen, Wenhe Wang, Yidong Yuan, Haifeng Zhang, Yubo Wang and Dongyan Zhao</i>	
A Micro-hotplate for MEMS Based Gas Sensor .....	749
<i>Gaoqiang Niu, Lingxiang He, Zhitao Yang, Changhui Zhao, Huimin Gong, Wei He and Fei Wang</i>	
Effects of Nano-SiO <sub>2</sub> Additions on Wettability and Interfacial IMC Growth of SAC Solder on Ni-xSiO <sub>2</sub> Composite Electroless Clad Layer .....	753
<i>Yong Wang, Xiaochen Xie, Ying Liu and Xiuchen Zhao</i>	
Effect of Chip Layout in Wafer on Molding and Fan-Out Wafer Level Packaging (FO-WLP) Technology .....	757
<i>Yang Li, Xuefei Ming and Yong Ji</i>	
Thermo-mechanical Modelling of Cu Wire Parallel Gap Micro-Resistance Welding Process .....	761
<i>Bingying Wu, Chunjin Hang, Yue Li, Yang Liu, Weiwei Zhang and Yanhong Tian</i>	
Leveraging 3D Packaging Technology to Enhance Integrated Circuits Security and Reliability .....	766
<i>Chunsheng Zhu, Yingjian Yan, Pengfei Guo and Junwei Li</i>	
Packaging Flat Micro Heat Pipe Using Low Melting Point Alloy .....	770
<i>Yi Luo, Chen Jia, Congming Li and Xiaodong Wang</i>	
Design and Implementation of High Power Semiconductor Laser Reliability Testing Platform.....	774
<i>Meng Su, Guoguang Lu, Huawei Xu and Linyi Huang</i>	
High Density On-Package Direct Cable Attachment for Hundred-Gbps Chip-to-Chip Interconnects .....	777
<i>Boping Wu</i>	
Improvement of Barrier Performance for Thin Film Encapsulation of Organic Light-Emitting Diodes by A	

Prior Planarization Process .....	780
<i>Cunping Qin, Jun Yang, Tao Xu, Xingwei Ding and Jianhua Zhang</i>	
Temperature and Stress Distribution of IGBT Module in DC Power Cycling Test with Different Switching Frequencies .....	785
<i>Chao Fang, Tong An, Fei Qin, Jingyi Zhao and Xuequan Yuan</i>	
Case Study of SBD Burnout Failure Caused by non Electric Overstress .....	791
<i>Guangning Xu and Jian Zhou</i>	
Design and Optimization of a Novel Silicone Rubber Elastic Button based on BPNN Model .....	795
<i>Siyu Wang, Zhi Liang, Zhangping Yang, Miao Cai, Daoguo Yang and Jinyang Li</i>	
Failure Analysis on Insufficient ACF Bonding Strength .....	801
<i>Weiming Li</i>	
Effect of Zincate Immersion Pretreatment on Corrosion Resistance of Electroless Plated Nickel-Phosphorus Film For Advanced Packaging .....	804
<i>Weixing Gan, Tao Hang and Ming Li</i>	
High Density Silicon Substrates for Processor-Memory Integration .....	808
<i>Baoxia Li, Zongxi Liu and Yanyan Su</i>	
Method to Prevent Thin Film Cracking of Thin Film Encapsulation in Flexible AMOLED .....	812
<i>Wei Ao, Yinghui Zhu, Jianhua Zhang, Yan Wang, Xiangchao Liu, Xiaogang Xin, Feng Gao and Chaochi Peng</i>	
Effect of Rapid Inducted Heating on the Microstructure of Solder Joint in IC .....	815
<i>Jibing Chen, Nong Wan and Juying Li</i>	
Effect of Eddy Current Inducted Heating on Optical Property and Thermostability of High Power LED .....	819
<i>Jibing Chen, Nong Wan, Juying Li and Yiping Wu</i>	
Light Extraction Efficiency Enhancement of 265nm UVC-LED with Micro-Array Structure .....	823
<i>Lei Wang, Daoguo Yang and Zhangping Yang</i>	
Effect of Different Material Systems on the Joint Properties of 30 $\mu$ m Pitch Micro Bumps .....	828
<i>Fengwei Dai, David Wei Zhang, Wenqi Zhang, Guojun Wang, Dengfeng Yang, Lin Chen, and Liqiang Cao</i>	
3D Module in Fan-out Packaging .....	832
<i>Lihua Zhan, Hao Li, Fuguo Zhu and Zhipeng Zhou</i>	
A Highly Reliable Cleaning Process .....	834



*Jun Zhang, Xiaofei Ye and Hailin Shi*

Research on LTCC - Based Flat Optocoupler Assembly Technology ..... 841

*Jun Zhang, Xiaofei Ye, Hailin Shi and Menglin Li*

Microstructure and Properties of AuSn20 Solder Ribbons Prepared by Rapid Solidification Process..... 850

*Chen Chen, Xuemei Zhang, Zhenhua Chen, Mingzhen Wei, Jian Zhou and Feng Xue*

Multi-chip Power Distribution Network Modeling and Analysis Based on Multi-Input Impedance ..... 854

*Jincan Zhang, Min Miao and Xiaole Cui*

Plasma Impact on PI Roughness ..... 860

*Qiang Cheng, Liming Guo and Li Zhang*

Fast Room-Temperature Sintering of Ag Nanoparticles on Polyethylene Terephthalate Film ..... 863

*Zhihao Zhang, Cunwei Wei, Jiajia Han, Huijun Cao, Yinggan Zhang, Yuan Gao and Yuping Xu*

Aging Effect on Defect Evolution and Shear Strength of Nano-silver Solder Joint ..... 867

*He Gong, Yao Yao, Jundong Wang, Shaobin Wang and Xu Long*

Design and Analysis of Microchannel for the Thermal Management of Multi-stacked LTCC Laminates..... 872

*Hejie Yu, Min Miao and Kai Zhao*

Thermal analysis and optimization of a thermally tunable grating filter with air trench structure ..... 876

*Fei Duan, Kai Chen and Yonglin Yu*

Research on the Influence of Dimpled Ceramic SMD on Mechanical Strength of Solder Joint in LTCC-based BGA Packages ..... 879

*Yuanqi Zeng, Yangyang Li, Hui Wang and Dong Dong*

Thermal Stress Analysis and Design Guidelines for Through Silicon Via Structure in 3D IC Integration ..... 883

*Yuanxiang Zhang, Jiankun Wang and Sijia Yu*

Numerical Simulation on Wafer Warpage During Molding Process of WLCSP ..... 886

*Mengke Yang, Fei Qin and Daquan Yu*

Research on Evolution Behaviors of SnPb Solder Under High Current Stressing ..... 891

*Huijun Cao and Zhihao Zhang*

Interconnection Reliability for MCM of Large Micromirror Arrays and High Voltage Driving ASIC Based on High-density Substrate ..... 895

*Zhenggao Hu, Gaowei Xu and Yaming Wu*

Research on Thermal Analysis of Iris Recognition Module Package Structure .....	899
<i>Zhangping Yang, Daoguo Yang, Lei Wang, Xiyu Wang and Miao Cai</i>	
Thermal Simulation Modeling of IGBT Module Using Silver Nanoparticle Sintering Material .....	904
<i>Hu Wang, Daoguo Yang, Xiyu Wang and Zhi Liang</i>	
Effect of Magnetic Field on Activation Performance of Silicon/Glass Dielectric Barrier Discharge .....	908
<i>Mingqiang Pan, Furong Yao, Jizhu Liu, Yangjun Wang and Lining Sun</i>	
Research on Mechanical Behavior of Through Silicon Via of 2.5D Interposer .....	913
<i>Jun Yang, Quanbin Yao, Pengrong Lin, Xiaochen Xie and Binhao Lian</i>	
Design, Fabrication, and Calibration of a Full Silicon WLP MEMS Sandwich Accelerometer .....	919
<i>Qifang Hu, Nannan Li, Chaoyang Xing, Wei Mei and Peng Sun</i>	
Preparation and Thermal Analysis of the Nano-Silver /Graphene Composite Material for Packaging Module .....	924
<i>Dongjing Liu, Yasong Fan, Haidong Yan, Haiying Lin, Haidong Zhu and Daoguo Yang</i>	
Effects of Sintering Temperature on Microstructure and Magnetic Properties of NiCuZn Ferrites for NFC Application .....	928
<i>Yan Yang, Huaiwu Zhang and Jie Li</i>	
Preparation of Metallic Materials for Electronic Packaging based on Space Environment .....	933
<i>Zhenchao Xia and Yahui Xue</i>	
Analysis of RF Transmission Performance of 3D TSV Interposer .....	937
<i>Zhengduo Wang, Liang Lang, Bo Wang and Fengshun Wu</i>	
Modulation of Gas Adsorption of SnS Monolayer by strain .....	941
<i>Fafei Hu, Huaiyu Ye and Hongyu Tang</i>	
An Exhaustive Search of the Optimal 6C Level Static Shielding Scheme for Rectangle TSV Arrays .....	944
<i>Xiaole Cui, Mengying Luo, Qiujun Lin, Min Miao and Yufeng Jin</i>	
Study on Ultrasonic Assisted Chemical Debonding Process .....	949
<i>Morgan Fan, Huiqing Ling, Tony Chen and Ming Li</i>	
Microwell as a Biomedical Device .....	952
<i>Zetian Wang, Xuanyang Li, Jing Chen and Yanming Xia</i>	
Reliability Investigation of 4H-SiC MOSFET Based on TCAD Simulation .....	956
<i>Houcai Luo, Yiping Huang, Kai Zheng, Chunjian Tan, Liming Wang, Shaogang Wang, Huaiyu Ye and Xianping Chen</i>	
The Breakdown Voltage of GaN HEMT is Restricted to The Structure Parameters of the Device: A Study	

Based on TCAD·····	961
<i>Liming Wang, Chunjian Tan, Houcai Luo, Shaogang Wang, Huaiyu Ye and Xianping Chen</i>	
Effect of MnZn Ferrite Doping on Magnetic and Electrical Properties of NiZnCu Ferrite Toroid Cores for Power Applications ·····	965
<i>Junchang Liu, Yunhui Mei, Xin Li and Guoquan Lu</i>	
Comparison of Performance Between PID and LADRC Algorithm in Linear Motion Platform ·····	969
<i>Yaobin He, Zhijun Yang and Qian Li</i>	
Simulation Analysis of Residual Stress of BGA Solder Joints After Reflow Soldering Based on Element Birth and Death Technology ·····	973
<i>Chunyue Huang, Shengjun Zhao and Xiangqiong Tang</i>	
Noise Analysis and Transmission Coding Optimization for High-speed Interconnection ·····	977
<i>Tianfang Chen, Min Miao, Bo Han, Zhensong Li, Kai Zhao and Xiaole Cui</i>	
Thermal Stress-Strain Simulation Analysis of BGA Solder Joint Reflow Soldering Process ·····	981
<i>Xiangqiong Tang, Chunyue Huang and Shengjun Zhao</i>	
Mechanical Response of Low Silver Lead-Free Solder under Dynamic Vickers Indentations ·····	987
<i>Cong Chen, Xiaoyan Niu and Linlin Shen</i>	
Research on Wafer Warpage and Internal Stress in the First Passivation Process of Embedded Si Fan-Out Package ·	990
<i>Shichao Yuan, Huiping Yu, Fei Qin, Daquan Yu, Min Xiang and Anwen Cai</i>	
Thermal Conductivity of Epoxy Resin Using Molecular Dynamics Simulation ·····	995
<i>Bensong Pi, Huiping Yu, Pei Chen, Anwen Cai, Fei Qin</i>	
A Novel Organic Coating Assisted Laser Drilling Method for TSV Fabrication ·····	999
<i>Xiquan Mai, Chen Yun, Dachuang Shi, Xun Chen, Xin Chen, Jian Gao, Chengqiang Cui, Yunbo He and Chingping Wong</i>	
Smith-ADRC Based Z Axis Impact Force Control for High Speed Wire Bonding Machine ·····	1003
<i>Yachao Liu, Jian Gao, Lanyu Zhang, Yun Chen, Hui Tang, Xin Chen and Chengqiang Cui</i>	
3 $\omega$ Method Based Experimental Measurements on Kapitza Resistance of Si/SiO <sub>2</sub> Interface ·····	1009
<i>Guang Zheng, Wenhui Zhu and Hu He</i>	
Flexible Strain Sensors Based on CNTs/PDMS Nanocomposite ·····	1013
<i>Dengji Guo and Hu He</i>	
Random Vibration Analysis of BGA with Different Size of SAC0307 Solder Ball ·····	1019

*Linlin Shen, Xiaoyan Niu and Cong Chen*

Highly Conductive Stretchable Wirings Composed of Ag Foils and Elastomer ..... 1022

*Cai-Fu Li, Hao Zhang, Wanli Li, Bowen Zhang, Tohru Sugahara, Zhi-Quan Liu and Katsuaki Sugauma*

Sintering Of Hybrid Nano Silver Paste Achieve Cone-Structured Cu Bonding in die attachment..... 1026

*Zhihui Liu, Zhuo Chen and Junhui Li*

Reliability Optimization of a 3D Packaged MEMS Thermal Wind Sensor..... 1032

*Shixuan Gao, Qingan Huang and Ming Qin*

Mathematical Simulation and Experimental Verification for Through Silicon Via with Additives ..... 1036

*Wei Liu, Fuliang Wang, Yan Wang and Wenhui Zhu*

Investigation on Copper Clip Bonding Structure for Power Package ..... 1042

*Linqi Liu, Qiang Liu, Xiaoyong Miao, Wei Jiang, Wei Lin and Lei Shi*

The Study on LED Droop of Flip-Chip GaN LED ..... 1047

*Yu Zhang, Xinfeng Zhu, Cheng Yao, Qiqin Wei and Jing Xiao*

Investigation of Microstructure and Growth Behavior of CoSn<sub>3</sub> Full Intermetallic Joints in Electronic Packaging ..... 1051

*Shuang Tian, Xuemei Zhang, Jian Zhou and Feng Xue*

Laser Grooving Technology Study at Dicing Process in Wafer Level Package ..... 1055

*Chao Chen, Ming Li and Kai Cao*

Optimization of Gold Wire Bonding Process for Microwave Components by DOE Method ..... 1059

*Xiaojian Liu, Nan Kang, Cui Jing, Lei Shi, Yawei Liu and Mengmeng Yin*

The Failure Analysis of LED Sulfur Corrosion ..... 1064

*Lan Chen, Huanxiang Xu, Hao Zhao and Zhenbo Zhao*

Investigation of Characteristics of the Capillary-driven Underfill Flow ..... 1070

*Kanglun Wang, Yan Wang and Wenhui Zhu*

A Novel Interposer Fabrication Method for Integration of Band-Pass Filter Applied in High Frequency ..... 1075

*Weibo Zhang, Gaowei Xu and Le Luo*

Research On Position&Force Control Based on Voice Coil Motor..... 1079

*Yunbo He, Chang Zhang, Jian Gao, Chengqiang Cui, Zhijun Yang, Xun Chen, Kai Zhang, Yun Chen and Hui Tang*

Laser bonding of glass and glass with constant temperature output ..... 1084

*Xianliang Fu, Rui Tian, Yi Li, Luqiao Yin and Jianhua Zhang*

Effects of Current Density and Concentration of $\text{Sn}^{2+}$ on Solder Voids .....	1089
<i>Liang Guo, Li Zhang and Ming Li</i>	
Effect of Oxide Layers on MONOS Device Performance Based on TCAD Simulation .....	1092
<i>Chuang Sun, Dandan Yi, Ming Li, Liming Gao</i>	
The Effect of Glass Frit Paste Levelling Property on Encapsulation .....	1097
<i>Rui Tian, Yi Li, Yibin Wang, Luqiao Yin and Jianhua Zhang</i>	
Mercury-Plated Iridium-Based Microelectrode Arrays for Trace Metal Detection .....	1102
<i>Zhi Cao, Haiping Shang, Yinghui Wang and Weibing Wang</i>	
Remaining Useful Life Estimation of Solder Joints using an ARMA Model Optimized by Genetic Algorithm ..	1108
<i>Yiwen Long, Hongwei Luo, Yue Zhi and Xiaoqiang Wang</i>	
Enhanced High Temperature Stability of Printed Cu Wirings Based On Big Cu Particle Ink, Ag Element Addition, and Intense Pulsed Light Sintering .....	1112
<i>Wanli Li, Linying Li, Caifu Li, Jinting Jiu and Katsuaki Suganuma</i>	
Case Study of No Fault Finds in Household Appliances.....	1116
<i>Gaoming Shi, Guanghua Yuan, Zhenfeng Xie, Xuanlong Chen and Cheng Chen</i>	
Influence of Observed Anelasticity of Cu on the Wafer Warpage Evolution During Thermal Processes .....	1119
<i>Gong Cheng, Gaowei Xu, Wei Gai and Le Luo</i>	
The Signal Integrity Design and Optimization of High Speed RF Optical Receiver Module .....	1123
<i>Juan Wei, Fengman Liu, Yu Sun, Huimin He, Pengcheng Ma, Man Zhao, Liqiang Cao, Haiyun Xue, Siwei Sun</i>	
$\text{Li}_0.33\text{La}_0.56\text{TiO}_3/\text{PEO}$ Composite Solid Electrolytes for Flexible All-Solid-State Lithium Batteries.....	1127
<i>Zhixiong Hu, Huangqing Ye, Jiahui Chen, Xianzhu Fu, Rong Sun and Ching-Ping Wong</i>	
Duration Effect of Pulsed High-Brightness Organic Light-emitting Diodes .....	1130
<i>Jiali Yang, Minyu Chen, Zhitian Ling, Yi Zhao, Chunya Li and Bin Wei</i>	
Investigation on the Joule Heating and Thermal Expansion in Flip Chip Package by Thermo-Electrical-Mechanic Coupling Analysis .....	1133
<i>Zhan Liu, Junhui Li and Wenhui Zhu</i>	
A Perceptive Study of Mechanical Chracterization of Grahene for Potential Applications in Thermal Management of Microsystems .....	1137
<i>Xiangdong Xue, Jianxin Yang, Yuming Wang and Wenyi Du</i>	

Numerical Study on a Novel Microchannel Structure Aiming for High Efficient Heat Dissipation·····	1145
<i>Fang Li, Hu He and Wenhui Zhu</i>	
A First Principles Study of Blue Phosphorene as A Superior Media for Gas Sensor ·····	1149
<i>Fanfan Niu, Daoguo Yang, Miao Cai, Xiaoling Li and Dongjing Liu</i>	
Magnetic and Dielectric Properties of Sm-doped M-type Barium Ferrites for LTCC Application ·····	1153
<i>Ximeng Yu, Jie Li, Yan Yang, Sheng Li, Daming Chen and Gongwen Gan</i>	
The Influence of Sintering Process Parameters On Thermal Properties of Nano-Silver Paste ·····	1157
<i>Xiuzhen Lu, Qianran Zhang, Abdelhafid Zehri, Wei Ke, Shirong Huang, Cheng Zhou, Weijuan Xia, Yanpei Wu, Lilei Ye and Johan Liu</i>	
Indium Sealing of Metal Shell for Precision Devices Packaging ·····	1161
<i>Xiaodong Wang, Xiaoli Yu, Xiaoyi Chen and Yi Luo</i>	
NiCo Oxyfluoride Non-Woven Cloth with Ultra-High Areal Capacitance for Flexible Supercapacitors ·····	1166
<i>Xuanyu Wang, Peichao Zou, Yang Wang, Wenhui Lai and Cheng Yang</i>	
The Influence of Surface Roughness of Silver Nanowires Electrode and Mechanical Properties of Polymeric Dielectric Layer on Capacitive Sensor Properties ·····	1170
<i>Yun Sun, Zijun Wang, Xiangfei Meng, Ying Wang, Chao Li and Yao Qi</i>	
Research on Solder Joints Between LED Chip and Heat Sink ·····	1174
<i>Wei Liu, X.X. Qian and J.T. Lin</i>	
Scaling Optical Communication for On-Chip Interconnect ·····	1178
<i>Mat Binggeli and Feng Li</i>	
A Synthetic Method for Extremely Stable Thin Film of CsPbBr <sub>3</sub> QDs and Its Application on Light-Emitting Diodes ·····	1184
<i>Hanguang Lu, Xuewei Du, Longshi Rao, Cunjiang Song, Yong Tang and Zongtao Li</i>	
A Packaged 2×2 Switch Array for Power Handling and Isolation Improvement ·····	1189
<i>Yulong Zhang, Zhuhao Gong, Xin Guo and Zewen Liu</i>	
Recent Advances in 3D Packaging for Medical Applications ·····	1193
<i>Yi Yang and Feng Li</i>	
Study on Interfacial Diffusion Mechanism of the Nonstoichiometric ratio TiN <sub>0.3</sub> and AlN composite in the process of sintering ·····	1198
<i>Zhanwen He, Mingzhi Wang and Jibing Chen</i>	

Design and Fabrication of Silicon-cavity Band-pass Filters Based on MEMS Technology .....	1202
<i>Peng Dong, Xiongwen Pan, Zhidong Li, Bin Duan, Qi Li and Qi Wang</i>	
Preparation and Characterization of Al <sub>2</sub> O <sub>3</sub> -AgNP hybrids for Application in Thermally Conductive Polymer Composites .....	1205
<i>Linlin Ren, Xiaoliang Zeng, Rong Sun, Jianbin Xu and Ching-Ping Wong</i>	
High Reliability Power Package Design for Automotive Requirements .....	1209
<i>Byong Jin Kim, Dong Su Ryu, Jia Yunn Ting, Hyeongil Jeon, Weng Tuck Chim and Nathan Whitchurch</i>	
Fabricating 3D BT-BN/epoxy Composites with High Dielectric Performance .....	1213
<i>Xiaodong Zhu, Suibin Luo, Shuhui Yu, Baojin Chu, Rong Sun and Chingping Wong</i>	
Design and Development of Power Module Co-Packaged with SiC GTO and SiC PiN .....	1219
<i>Yingkun Yang, Lei Gao, Zhiqiang Li, Kun Zhou, Lin Zhang, Yunfei Gu, Yunhui Mei, Long Zhang and Juntao Li</i>	
A Novel Hole-Path and Carrier-Stored IGBT with Low Switching Loss and On State Voltage .....	1223
<i>Shaogang Wang, Chunjian Tan, Liming Wang, Houcai Luo, Shaolin Li, Huaiyu Ye and Xianping Chen</i>	
Model and Analysis of Planar Spiral Inductor Based on Package Substrate .....	1227
<i>Haiyan Sun, Wenjun Sun, Ling Sun, Jicong Zhao, Jiaen Fang, Xiaoyong Miao and Honghui Wang</i>	
FE Analysis the Effect of Bond Wire and Solder Failure On Resistance and Temperature of IGBT .....	1232
<i>Jingyi Zhao, Fei Qin, Tong An, Xiaorui Bie, Chao Fang and Xuequan Yuan</i>	
New Surface Treatment Method for Silver Alloy Wire and Its Performance Evaluation .....	1237
<i>Bin Yang, Chengqiang Cui, Yu Zhang, Kai Zhang, Zhangqiao Zhou, Xun Chen, Xin Chen, Jian Gao, Yunbo He, Hui Tang and Yun Chen</i>	
Electrodeposition of Anisotropic NiFe Thin Films for Integrated High-Frequency Micro-Inductor ....	1241
<i>Linlin Yang, Liyin Gao, Chunhuan Chen and Zhiquan Liu</i>	
Study on Electrostatic Discharge Damage and Defect Damage Failure Analysis Technology for Semiconductor Devices .....	1246
<i>Lin Hu, Qizheng Ji and Shengzong He</i>	
Study on the Composite Coating Process of Oxide Particles in Magnetic Thin Films .....	1250
<i>Biao Li, Guangming Liu and Zhiquan Liu</i>	
Room-Temperature Synthesis of Cesium Lead Halide Perovskite Nanorods .....	1254
<i>Xuwei Du, Zongtao Li, Xinrui Ding, Hanguang Lu, Longshi Rao and Yong Tang</i>	

EMC Modeling and Simulation in Quad Flat Package .....	1259
<i>Haiyan Sun, Shoukun Huang, Ling Sun, Jicong Zhao, Yihong Peng, Jiaen Fang, Xiaoyong Miao and Honghui Wang</i>	
Mechanism of Ni <sub>3</sub> Sn <sub>4</sub> Rapid Formation of Sn-Ni Mixed Particles Paste in Ultrasound-Assisted TLP for Power Electronic Chip Attachment .....	1263
<i>Jiayi Huang, Hao Pan, Hao Liu, Fanqi Yin, Jiaao Yu, Hongjun Ji and Mingyu Li</i>	
Electrical-Thermal Co-simulation for LFBGA .....	1269
<i>Haiyan Sun, Bo Gao, Ling Sun, Jicong Zhao, Yihong Peng, Jiaen Fang, Xiaoyong Miao and Honghui Wang</i>	
Prognostics and Health Management Technology of LED Lamp .....	1273
<i>Guoguang Lu, Canxiong Lai and Bin Yao</i>	
Processes-based Multistep Simulation of Thermal-mechanical Reliability of a 3D-TSV MEMS .....	1278
<i>Qinghua Zeng, Jing Chen and Yufeng Jin</i>	
Effect of ZnS Size On the Dielectric and Energy Storage Properties of ZnS/Polymer Composites .....	1283
<i>Zijie Song, Suibin Luo, Chao Wang, Shuhui Yu, Rong Sun and Chingping Wong</i>	
Significantly Improved Stability of PDMS-Packaged Silver Nanowire Film under Multiple Environments ..	1288
<i>Kaiqing Wang, Jianzhong Wang, Yunxia Jin and Fei Xiao</i>	
Comparison Studies on Joint Process for ENEPIG Surface Finished Chip for Double-sided Cooling Module	1293
<i>Shuxun Lou, Ju Xu, Long Zhang and Lei Gao</i>	
Synthesis and Characterization of 3D CoMoO <sub>4</sub> /rGO Aerogel for Supercapacitor Electrodes .....	1297
<i>Chao Wang, Zhishu Guan, Min Wei, Shuhui Yu, Rong Sun and Chingping Wong</i>	
Electrical Research of Silicon Substrate Packaging Technology Based on the Cavity .....	1301
<i>Man Zhao, Fengman Liu, Pengcheng Ma, Meiju Zhang, Lian Zheng, Hongxiang Zhang and Liqiang Cao</i>	
Highly Conductive, Flexible PU/PANI Based Conductive Adhesives for Flexible Electronics .....	1305
<i>Shaocun Yan, Hongru Ma, Zhe Li, Yanqing Ma and Lei Ma</i>	
Application of Ag/graphene Composites in Flexible Electrical Conductive Adhesives .....	1309
<i>Hongru Ma, Shaocun Yan, Zhe Li, Yanqing Ma and Lei Ma</i>	
Molecular Dynamics Study of Copper Wire Bonding Process .....	1312
<i>Xiyou Wang, Daoguo Yang, Zhangping Yang and Lei Wang</i>	
Dual Effects of CTAB on Co-deposition of SiC/Cu in Micro Via .....	1317
<i>Houya Wu, Yan Wang, Zhiyi Li, Fuliang Wang and Wenhui Zhu</i>	



Mechanisms of Power Module Metallization Degradation Under Ageing·····	1322
<i>Xuequan Yuan, Tong An, Fei Qin, Jingyi Zhao and Chao Fang</i>	
Highly Sensitive Pressure Sensing Coatings Based on Silicone/Expandable Microspheres Composites ····	1326
<i>Yuhan Zhang, Zhengqing Zuo, Tianyu Shao, Peng Zheng and Zhuo Li</i>	
A Numerical Model for Joule heating in Sn Solder Balls of Two Different Sizes. ·····	1329
<i>Anil Kunwar, Shengyan Shang, Peter Raback, Xueguan Song, Prafulla Bahadur Malla, Yunpeng Wang and Haitao Ma</i>	
Investigation on Highly Efficient Thermal Interface Materials: A New Attempt to Bond Heat-Conducting Particles Using Low-Melting-Temperature Alloy·····	1333
<i>Song Wei, Lijun Zhou and Jingdong Guo</i>	
Analysis and Optimization of Coupling Noise in TSV Array ·····	1337
<i>Zheng Mei, Gang Dong, Weijun Zhu, Jingrui Chai, Junping Zheng and Dongliang Song</i>	
Signal Integrity Design For QSFP Interface Applicated in RF Optical Transmitter Module ·····	1343
<i>Pengcheng Ma, Fengman Liu, Man Zhao, Juan Wei, Haiyun Xue, Yu Sun, Siwei Sun, Liqiang Cao</i>	
A Study on Pd Distribution Effect on the Reliability of Au Coated PCC Wire Bonding·····	1346
<i>Seokho Na and Sungho Jeon</i>	
Application of Three-Dimensional X-Ray Microscopy in Failure Analysis for Sealed Relay ·····	1351
<i>Daotan Lin</i>	
Synthesis of Copper Nanoparticles Using Copper Hydroxide ·····	1355
<i>Xian Zeng, Yu Zhang, Chengqiang Cui, Kai Zhang, Xun Chen, Xin Chen, Jian Gao, Yunbo He and Hui Tang</i>	
Resin-Free Color Converter Based on Phosphor-in-Glass for Laser-excited White Lighting ·····	1359
<i>Yang Peng, Yun Mou, Xingxing Liu, Mingxiang Chen and Xiaobing Luo</i>	
Effect of in Addition on the Microstructure and Mechanical Properties of Sn-Au-Cu-In Solders ·····	1363
<i>Siqi Yin, Mingliang Huang and Yu Chen</i>	
Effect of Soldering Sequences on Cu-Ni interaction in flip-chip interconnects·····	1368
<i>Jiameng Kuang and Mingliang Huang</i>	
A Novel Approach to Calculate the Thickness Distribution of Thin Film Deposited by Multi-Target Co-Sputtering System ·····	1372
<i>Guo Zhu, Jiangping Sun and Zhiyin Gan</i>	
Cu film surface reduction through formic acid vapor/solution for 3-D interconnection ·····	1378
<i>Wenhua Yang, Chenggong Zhou, Jie Zhou, Yangting Lu, Yingchun Lu and Tadatomo Suga</i>	

Research on the Board Level Reliability of High Density CBGA and CCGA under Thermal Cycling ·	1382
<i>Liangyu Tong, Changshun Jiang and Guojun Ao</i>	
Batch-Mode $\mu$ USM Process for Surrounding Air Cavity and TCV Holes of AlN Ceramic Substrate Application for Patch Antenna ·····	1387
<i>Yanming Xia, Shenglin Ma, Lu Song, Tao Wang, Zetian Wang, Xuanyang Li, Jing Chen, Wei Wang and Yufeng Jin</i>	
Study on 3D stack package with anodic alumina substrate ·····	1391
<i>Yan Luo, Lichun Wang, Mifeng Liu, Yong Zhao, Weiwei Wu and Weipeng Ren</i>	
The influence of solder on thermal stress in FCOL devices ·····	1396
<i>Xin Tao, May Li and Jun Wang</i>	
Effect of Indium, Bismuth and Copper Doping on Microstructure and Mechanical Properties of Sn5Sb and Sn3.5Ag Lead Free Solder Alloys ·····	1400
<i>Zhu hao Liu, Hongfa Pan, Yibo Wang, Ling Xu, Jicun Lu, Daike Wu, Jian Wu, Ming Li and Liming Gao</i>	
Si Interposer with Multiple Cavities for 3D Stacked Fan-Out Package ·····	1406
<i>Xinxin Hu, Rongfeng Luo, Zhen Shen, Han Cai, Jun Yan, Dan Gong and Shenglin Ma</i>	
The Study of Thermally Induced Warpage of BGA Package during Reflow Soldering ·····	1411
<i>Bin Yao, Xiaofeng Wang and Yabing Zou</i>	
Wettability and Shear Strength of SAC305 Based Composite Solder with co-doping X (Al <sub>2</sub> O <sub>3</sub> or Ni) and CNTs Reinforcements ·····	1415
<i>Liping Mo, Sicong Hu, Zheng Zhou, Fengshun Wu, Shiyuan Liu and Hui Liu</i>	
Fabrication of Phosphor Pillar Based on Electrohydrodynamic for High Angular Color Uniformity of White Light-emitting Diodes ·····	1421
<i>Jinglong Zou, Feng Han, Zefeng Zhang, Sheng Liu and Huai Zheng</i>	
Light Extraction Enhancement of Deep Ultraviolet Light-Emitting Diodes by Using Aluminum Reflector Cup ·····	1426
<i>Xingxing Liu, Yang Peng, Yun Mou, Hao Cheng and Mingxiang Chen</i>	
Enhancing Optical Performance of Quantum Dot-Converted LEDs via Electrospun Fiber Rod ·····	1429
<i>Guanwei Liang, Junchi Chen, Shudong Yu, Siyang Feng, Caiman Yan, Binhai Yu and Zongtao Li</i>	
Effect of LED Chip Displacement on Its Optical Performance and Reliability ·····	1433
<i>Naiqi Pei, Qi Chen, Run Hu and Xiaobing Luo</i>	

Research on Centrifugal Sedimentation for Improving Luminous Flux of the Quantum-Dots LED Devices··	1437
<i>Caiman Yan, Huiyu Wang, Kai Cao, Dongqiang Fan, Jiasheng Li, Zongtao Li and Xingrui Ding</i>	
Fabrication and Characterization of AlN Based Piezoelectric Micro-Machined Ultrasonic Transducer for Contact Sensing .....	1442
<i>Dan Gong, Han Cai, Jiwei Li, Shenglin Ma and Yihsiang Chiu</i>	
VUV/O <sub>3</sub> Activated Bonder for Low-Temperature Direct Bonding of Si-Based Materials .....	1448
<i>Jikai Xu, Chenxi Wang, Xiaoyun Qi, Bin Wu, Shicheng Zhou and Yanhong Tian</i>	
Room-Temperature Bonding and Debonding of Glass and Polystyrene Substrates Based on VUV/O <sub>3</sub> Activated Bonding Method .....	1453
<i>Xiaoyun Qi, Chenxi Wang, Qiushi Kang, Daoyuan Li, Yanhong Tian and Lingchao Kong</i>	
Research on Vibration Fatigue Reliability of DIP Surface-Mounted Solder Joint after Pin Bend .....	1457
<i>Lu Tao, Bin Zhou and Xiao He</i>	
Enhancing Color Conversion Efficiency of Quantum Dot LED by Electric Field Assistance .....	1461
<i>Junchi Chen, Guanwei Liang, Shudong Yu, Zhi Li, Hanguang Lu, Binhai Yu and Zongtao Li</i>	
Optimization of PCB Board to Improve Thermomechanical Reliability of Lead-Free Solder Ball Joint ....	1466
<i>Ling Xu, Shengrui Zhou and Jicun Lu</i>	
Influence of Solder Ball Volume on Mechanical Shock Reliability of Right-Angle Solder Interconnects .....	1472
<i>Wu Yue, Minbo Zhou and Xinping Zhang</i>	
The Performance of Sintered Nanocopper Interconnections for High Temperature Device .....	1476
<i>Qipeng Liu, Huaiyu Ye, Xianping Chen, Jie Zhu, Huankun Zhang, Jiangsong Zhang, Jingguo Zhang, Ligen Wang, Sau Wee Koh and Guoqi Zhang</i>	
Investigation on Two Realizations of Miniaturized Integrated Passive Devices in a SiP Transceiver Front-End ·	1479
<i>Yu Ban and Jie Liu</i>	
Interfacial Reaction of Micro Co-P/Solder/Co-P Interconnection Under Large Temperature Gradients .....	1483
<i>Fei Du, Chunhong Zhang, Guisheng Gan and Donghua Yang</i>	
The Influence of Microstructure Characteristic on the Electromigration Behavior Of Line-Type Sn <sub>58</sub> Bi Solder Joints .....	1488
<i>Yi-Kang Li, Lei Guo, Zheng-Chao Liang, Hongbo Qin, Xing-He Luan and Bin Hou</i>	
Study on the Reliability of Large Size LCCC .....	1492
<i>Liquan Wang, Suhuan Wang and Songyin Sui</i>	

Diffusion Films Based on PMMA and Their Application on Color Uniformity of Imitating Lumen LED·····	1496
<i>Jiadong Yu, Shudong Yu, Yong Tang, Guanwei Liang and Zongtao Li</i>	
Process Development OF Ultra-Fine Pitch High Density Micro Bumps ·····	1500
<i>Dengfeng Yang, Fengwei Dai and Wenqi Zhang</i>	
SIMS Analysis of Impurity in HgCdTe Epilayers of Infrared Focal Plane Array ·····	1504
<i>Canxiong Lai, Shaohua Yang, Guoguang Lu, Songmin Zhou and Xi Wang</i>	
Analysis of the Failure of Inductor Coil Caused by Tining ·····	1507
<i>Tao Hong, Yongda Hu, Shengxiang Bao, Jie Chen, Zongzhi Duan, Qiang Li, Chuan Luo, Libo Ai and Pengbo Jiang</i>	
Challenges in Predicting the Solder Interconnect Degradation of High Power Electronics ·····	1511
<i>Xiujuan Zhao, Hans de Vries, Piet Watte and Ger van Hees</i>	
A Highly Dense TSV Switch Array Integrated with LTCC Control Unit ·····	1518
<i>Fei Zhao, Yuanlan Dang and Shiwang Jia</i>	
Miniaturization of Low Temperature Co-fired Ceramic Packaging for Microwave Filters·····	1524
<i>Yanlin Li and Xu Zhu</i>	
Reliability Evaluation of Interconnection in COM Package·····	1528
<i>Jin Wang, Jianming Li, Ke Du, Xinnan Hou, Qian Wang and Jian Cai</i>	
Hygrothermal Stress Analysis for a Micro-Camera Module Under the Moisture Sensitivity Level One ····	1533
<i>Zhihao Zhao, Sangpu Yang and Jun Wang</i>	
Effect of Zinc Oxide Filler on Electrical Conductivity of Crosslinked Polyethylene Nonlinear Composites ·····	1538
<i>Gaolang Dong and Limin Ma</i>	
The Research of Application Reliability And Failure Modes Of Wire Bonding Process ·····	1542
<i>Min Kang, Di Liu and Heran Zhao</i>	
A Review On the Copper Bond Pad Application in Wire Bond Technique ·····	1546
<i>Jinzhi Liao, Yan Chen, Xiaomin Li, Chao Fu, Younan Hua and Bisheng Wang</i>	
A New Multilayer AiP Solution Based on Organic Substrate ·····	1554
<i>Shengjuan Zhou, Qian Wang, Xuesong Zhang Jian Cai and Yu Chen</i>	
Discussion on Failure Mechanism and Corresponding Evaluation Technology for the Reliability of IC's Applications in Board-Level Assembly ·····	1558
<i>Xiao He, Jianghua Shen, Tao Lu and Zeya Peng</i>	

Wafer-level Integration of Micro Heaters On an Alkali Vapor Cell for Chip-Scale Atomic Magnetometers ···	1564
<i>Guoliang Li, Jintang Shang, Jin Zhang and Yu Ji</i>	
Polymorphic Impedance Matching Technique for MEMS Phase Shifter ·········	1568
<i>Shumin Zhao, Hao Chi Zhang and Jiahao Zhao</i>	
Corrosion of Cu/Ni/Au Coating Caused by F Element··········	1575
<i>Liyao Zhao and Zebin Kong</i>	
High Power Module Package Mounting and Temperature Cycling Reliability Study by Simulation ···	1578
<i>Richard Qian, Alex Yao, Bruce Xu, Yong Liu and Ch Chew</i>	
Application of Worst Case Analysis to Failure Analysis of Hybrid IC ·········	1585
<i>Tong Wang, Xu Wang, Meng Meng, Zhimin Ding and Ming He</i>	
Highly Thermally Conductive and Light Weight Copper/Graphene Film Laminated composites for Cooling Applications ·········	1588
<i>Nan Wang, Shujing Chen, Amos Nkansah, Christian Chandra Darmawan, Lilei Ye and Johan Liu</i>	
Structure and Luminescence Properties Study of Eu <sup>2+</sup> doped Ca <sub>2</sub> Al <sub>2</sub> -xSi <sub>1+x</sub> O <sub>7</sub> -xN <sub>x</sub> Phosphors Based on Size-Mismatch Model ·········	1593
<i>Lei Chen, Gang Jing and Jintian Lin</i>	
Facile Way to Fabricate High Quality White LED with Yellow Graphene Quantum Dots ·······	1598
<i>Luqiao Yin and Jipeng Zhou</i>	
Influence of P3HT Molecular Weight on Film Processing and Solar Cell Performance ·······	1602
<i>Junle Yu, Jie Tang, Chao Wang, Yanqiong Zheng, Chihaya Adachi, Chenghui Zeng</i>	
Modeling, Analysis and Implementation of Junction-to-Case Thermal Resistance Measurement for Press-Pack IGBT Modules ·········	1605
<i>Helong Li, Yafei Wang, Ashley Plumpton, Yangang Wang, Daohui Li, Xiaoping Dai and Guoyou Liu</i>	
Research on the Effect of Mechanical Bending on Signal Transmission Characteristics of FPC ·····	1611
<i>Ruiqiang Tang, Dejian Zhou and Ting Lei</i>	
Design of Incremental Grating Ruler Online Measuring- Displacement System Based on LabVIEW ·	1615
<i>Yanfeng Li, Zhijun Yang, Han Sun, Shaowang Xiong and Qian Li</i>	
Influence of Different Materials on Thermal Stress of Conical TSV ·········	1619
<i>Gudi Chen, Zhiqi Wang and Weiyin Wang</i>	

Numerical Study on E-jet printing Cone Forming of the Insulating Nozzle Structure .....	1624
<i>Zhiqi Wang, Dejian Zhou, Xiaoyong Chen and Guidi Chen</i>	
Design and Implementation of Energy Efficiency Metering System for Multi-terminal Flexible DC Transmission .....	1629
<i>Jiangming Zhang, Li Yao and Yingjun Hu</i>	
A 2.4-GHz Digitally Controlled Ring Oscillator Based on MOS Capacitors.....	1635
<i>Xin Geng, Zixuan Wang, Yufeng Guo, Cong Zhang, Xiaojuan Xia, Haozheng Li and Yuhui Han</i>	
A 0.6-V Supply Two-Step Time-to-Digital Converter Using Dynamic Threshold Technology .....	1638
<i>Cong Zhang, Zixuan Wang, Xiaojuan Xia, Xin Geng, Yufeng Guo, Zichen Tian and Mei Liu</i>	
Fatigue Damage Assessment of LED Chip Scale Packages with Finite Element Simulation .....	1642
<i>Jiajie Fan, Wei Chen and Dan Xu</i>	
Fabrication and Characterization of Nickel-Gold Plateable LTCC Substrates Based on Borosilicate Glass/Al <sub>2</sub> O <sub>3</sub> System .....	1649
<i>Huanhuan Wan, Weijun Zhang and Zhuofeng Liu</i>	
Electromigration in Flip Chip with Cu pillar Having A Shallow Sn-3.5Ag Solder Interconnect .....	1653
<i>Haoliang Zhang, Junhui Li and Wenhui Zhu</i>	
Graphene-like Monolayer Yttrium Nitride: A Moderate Semiconductor and Pronounced Electronic Insensitivity to Strain.....	1657
<i>Heping Cui, Kai Zheng, Houcai Luo and Xianping Chen</i>	
Thermal Analysis on the Degradation of GaN HEMTs .....	1661
<i>Bin Zhou, Ruguan Li, Zhiyuan He, Yun Huang, Si Chen and Xing Fu</i>	
Study on De-Embedding Approach of Non-Coaxial Microwave Device Test Fixtures .....	1666
<i>Shouhong Chen, Ping Yang, Jun Ma, Zhuang Wang and Xuelong Yan</i>	
Evaluation and Failure Mechanism of High Power Semiconductor Laser Packaging.....	1671
<i>Guoguang Lu, Canxiong Lai and Bin Yao</i>	
Interconnect Reliability of Low Temperature Solder for Potential Application in Enterprise Computers, Portable, and Automotive Electronics (Part 1) .....	1675
<i>Paul Wang and David He</i>	
Compensation Method for Die Shift in Fan-Out Packaging.....	1681
<i>Yue Sun, Fengze Hou, Feng Chen, Haiyan Liu, Hengyun Zhang, Peng Sun, Tingyu Lin and Liqiang Cao</i>	

Influence Factor Analysis of Thermal Resistance for Plastic Package .....	1687
<i>Wenhua Hu, Jian Xu and Peng Sun</i>	
The Measurement of Dynamic Junction Temperature for LED Flash Units of Camera .....	1692
<i>Brian Shieh, Fangyun Zeng, Guoming Yang and S. W. Ricky Lee</i>	
Ultrasonic-Assisted Soldering of SAC0307 Solder with Nano-Particles Active-Flux .....	1696
<i>Daquan Xia, Guisheng Gan, Xin Liu, Donghua Yang, Yiping Wu and Yufeng Zhou</i>	
Synthesis of Size-Controlled Pure Copper Nanoparticles for Interconnect .....	1702
<i>Tao Lai, Chengqiang Cui, Yu Zhang, Kai Zhang, Tao Chen, Xun Chen, Xin Chen, Jian Gao, Yunbo He, Hui Tang and Yun Chen</i>	
Study on the Structure of Vertical Through Silicon Via with Aspect Ratio 2.5:1 for CMOS Image Sensor .....	1706
<i>Lijun Chen, Fengwei Dai and Wenqi Zhang</i>	
Microstructure Evolution and Properties Evaluation of a Novel Bondline Based on Cu@Sn Preform During Temperature Treatment .....	1709
<i>Hongyan Xu, Jianqiang Li, Puqi Ning and Ju Xu</i>	
Development on Super-thin & High-Pixel CMOS Image Sensor Module .....	1716
<i>Mark Huang, Huisheng Han, Huabin Wu, Chuangwen Huang and Weiqing Zhang</i>	
Case Study of Resistor Failure Caused by Bi Migration and Preventive Measures .....	1720
<i>Jintao Chen, Liyuan Liu, Fuyao Mo, Binruo Zhu, Yin Zhang and Zhen Gu</i>	
Research on the Photoelectric Properties of Flexible Photodetectors .....	1723
<i>Xiaoyong Chen, Dejian Zhou, Yulai She and Tianshou Liang</i>	
Research of Inkjet Printing Process for Flexible Electronic Interconnect Structures .....	1728
<i>Siming Gong, Kailin Pan, Wenhui Wang, Kai Fan, Hao Cheng and Chen Guo</i>	
Study of the Interaction Energy at the Composite Interface between PDMS and Functionalized Graphene Using Molecular Dynamics Simulations .....	1735
<i>Kai Fan, Kailin Pan, Siming Gong, Wenhui Wang, Hao Cheng and Chen Guo</i>	
Design and Analysis of Self-Similar Serpentine Interconnects for Stretchable Electronics .....	1741
<i>Fan Yang, Yasong Wang, Xiaole Kuang, Yaoyao Nie and Wei Xia</i>	
Effect of Temperature Gradient on Interfacial Reactions in Cu/Sn-9Zn/Ni Solder Joints during Aging .....	1744
<i>Ning Zhao, Mingyao Wang, Yi Zhong, Haitao Ma and Yunpeng Wang</i>	

Growth Mechanism of Cu <sub>3</sub> Sn Grains in the (111)Cu/Sn/Cu Micro Interconnects .....	1748
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*Yi Zhong, Ning Zhao, Wei Dong, Yunpeng Wang and Haitao Ma*